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2SC2853, 2SC2854

Silicon NPN Epitaxial

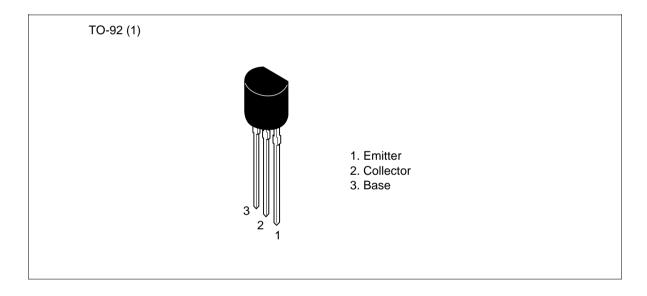


ADE-208-1078A (Z) 2nd. Edition Mar. 2001

Application

• Low frequency amplifier

Outline



2SC2853, 2SC28<u>5</u>4

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	2SC2853	2SC2854	Unit
Collector to base voltage	V_{CBO}	90	120	V
Collector to emitter voltage	V _{CEO}	90	120	V
Emitter to base voltage	V _{EBO}	5	5	V
Collector current	I _c	100	100	mA
Emitter current	I _E	-100	-100	mA
Collector power dissipation	P _c	400	400	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

Electrical Characteristics ($Ta = 25^{\circ}C$)

		2SC2853 2		2SC	2SC2854				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	90	_	_	120	_	_	V	$I_{c} = 10 \mu A, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	90	_	_	120	_	_	V	$I_{C} = 1 \text{ mA}, R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	5	_	_	V	$I_{E} = 10 \mu A, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	0.1	_	_	0.1	μΑ	$V_{CB} = 70 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	0.1	_	_	0.1	μΑ	$V_{EB} = 2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	250	_	800	250	_	800		$V_{CE} = 12 \text{ V}, I_{C} = 2 \text{ mA}^{*2}$
Collector to emitter saturation voltage	V _{CE(sat)}	_	0.05	0.10	_	0.05	0.10	V	$I_{\rm C}$ = 10 mA, $I_{\rm B}$ = 1 mA* ²
Base to emitter saturation voltage	$V_{BE(sat)}$	_	0.7	1.0	_	0.7	1.0	V	-
Gain bandwidth product	f _T	_	310	_	_	310	_	MHz	$V_{CE} = 6 \text{ V}, I_{C} = 10 \text{ mA}$
Collector output capacitance	Cob	_	3	_	_	3	_	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0,$ f = 1 MHz

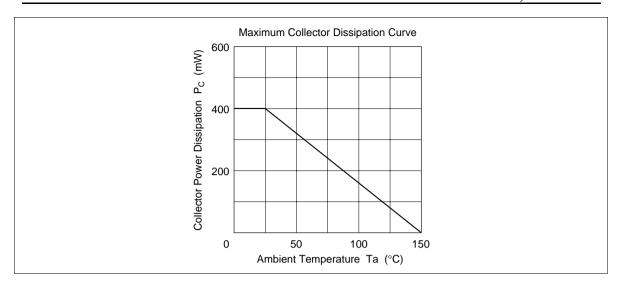
Notes: 1. The 2SC2853 and 2SC2854 are grouped by $h_{\rm FE}$ as follows.

2. Pulse test

D E 250 to 500 400 to 800

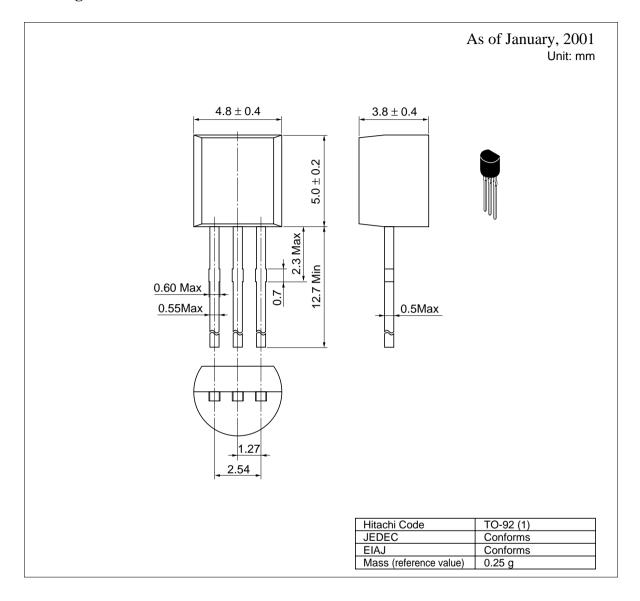
See characteristic curves of 2SC2855 and 2SC2856.

2SC2853, 2SC2854



2SC2853, 2SC2854

Package Dimensions



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